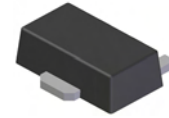


Features

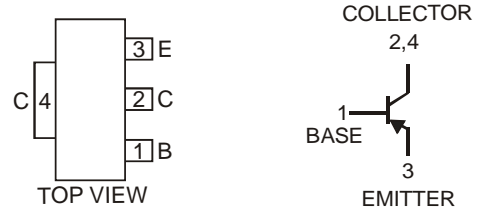
- Epitaxial Planar Die Construction
- Complementary NPN Type Available (DXTA42)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**



SOT89-3L

Mechanical Data

- Case: SOT89-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish — Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.072 grams (approximate)



Schematic and Pin Configuration

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	-300	V
Collector-Emitter Voltage	V _{CEO}	-300	V
Emitter-Base Voltage	V _{EBO}	-5	V
Continuous Collector Current	I _C	-500	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ T _A = 25°C	P _D	1	W
Thermal Resistance, Junction to Ambient (Note 3)	R _{θJA}	125	°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 4)						
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-300	—	—	V	I _C = -100μA, I _E = 0
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-300	—	—	V	I _C = -1mA, I _B = 0
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5	—	—	V	I _E = -100μA, I _C = 0
Collector-Base Cut-off Current	I _{CBO}	—	—	-0.25	μA	V _{CB} = -200V, I _E = 0
Emitter-Base Cut-off Current	I _{EBO}	—	—	-0.1	μA	V _{EB} = -3V, I _C = 0A
ON CHARACTERISTICS (Note 4)						
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	—	-0.5	V	I _C = -20mA, I _B = -2mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	—	—	-0.9	V	I _C = -20mA, I _B = -2mA
Static Forward Current Transfer Ratio	h _{FE}	25	—	—	V	I _C = -1mA, V _{CE} = -10V
		40	—	—		
		25	—	—		
SMALL SIGNAL CHARACTERISTICS						
Gain-Bandwidth Product	f _T	50	—	—	MHz	I _C = -10mA, V _{CE} = -20V, f = 100MHz
Output Capacitance	C _{obo}	—	—	6	pF	V _{CB} = -20V, f = 1MHz

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 4. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%.

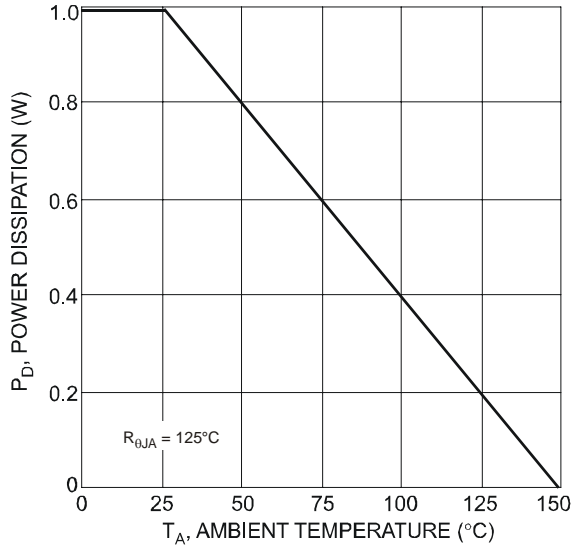


Fig. 1, Power Dissipation vs. Ambient Temperature (Note 3)

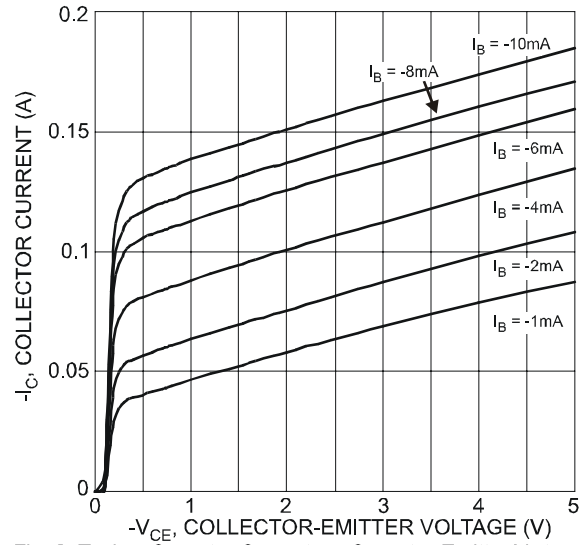


Fig. 2, Typical Collector Current vs. Collector-Emitter Voltage

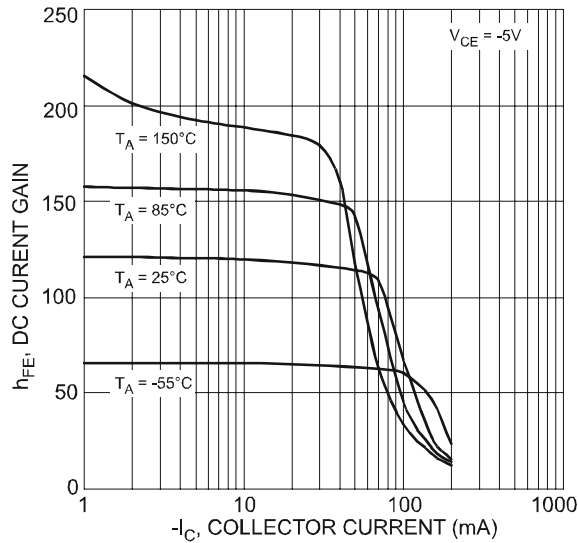


Fig. 3, Typical DC Current Gain vs. Collector Current

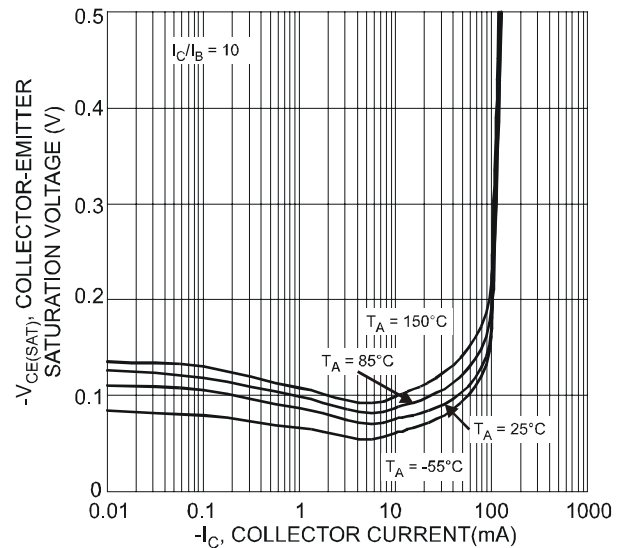


Fig. 4, Typical Collector-Emitter Saturation Voltage vs. Collector Current

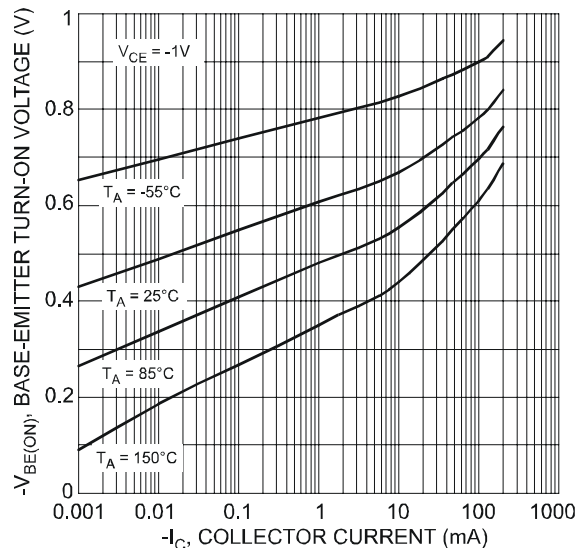


Fig. 5, Typical Base-Emitter Turn-On Voltage vs. Collector Current

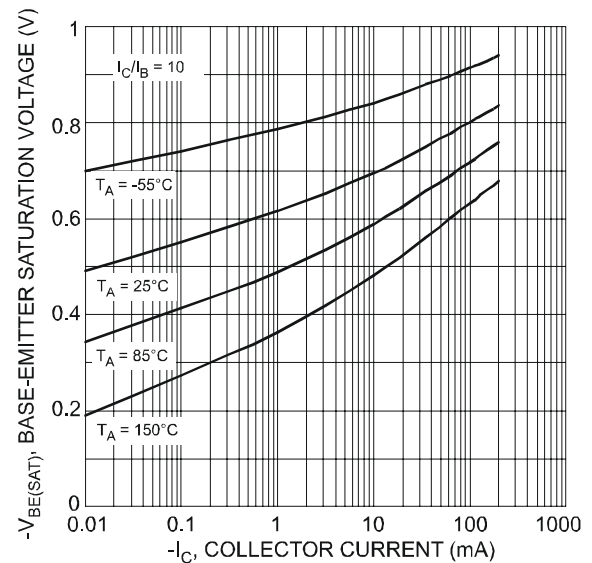


Fig. 6, Typical Base-Emitter Saturation Voltage vs. Collector Current

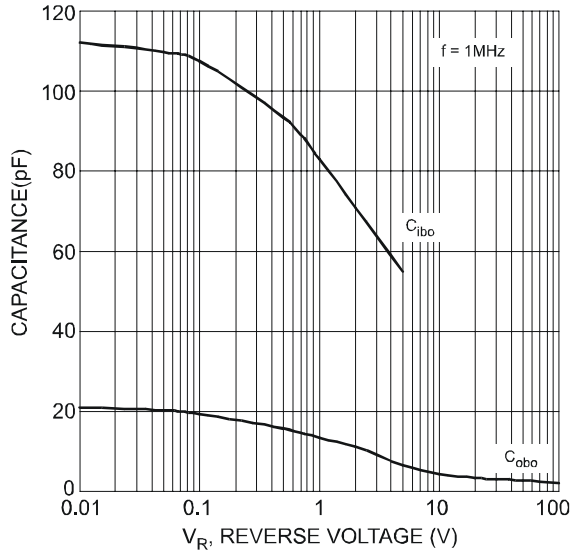


Fig. 7, Typical Capacitance Characteristics

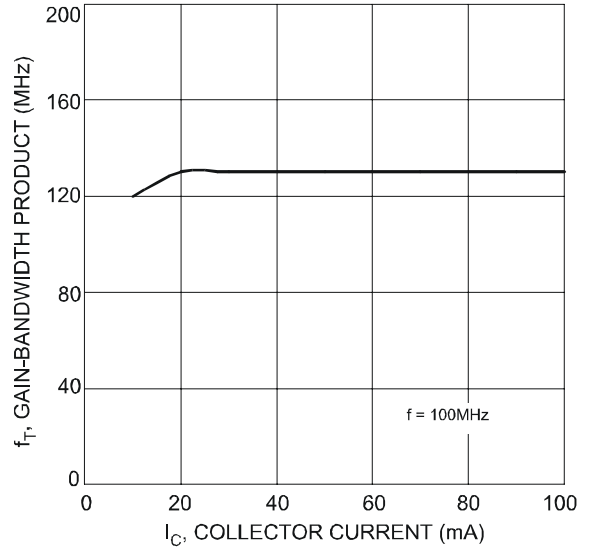


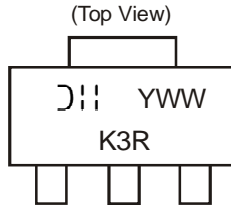
Fig. 8, Typical Gain-Bandwidth Product vs. Collector Current

Ordering Information (Note 5)

Device	Packaging	Shipping
DXTA92-13	SOT89-3L	2500/Tape & Reel

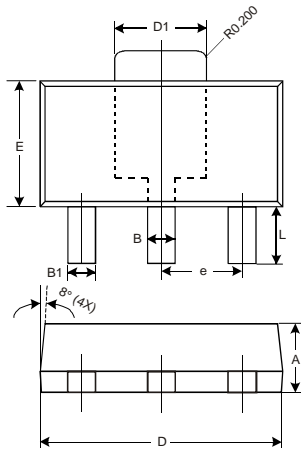
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/ap02007.pdf>.

Marking Information



DII = Manufacturer's Code Marking
K3R = Product Type Marking Code
YWW = Date Code Marking
Y = Last digit of year ex: 7 = 2007
WW = Week code 01 - 52

Package Outline Dimensions



SOT89-3L			
Dim	Min	Max	Typ
A	1.40	1.60	1.50
B	0.45	0.55	0.50
B1	0.37	0.47	0.42
C	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.50	1.70	1.60
E	2.40	2.60	2.50
e	—	—	1.50
H	3.95	4.25	4.10
L	0.90	1.20	1.05
All Dimensions in mm			

Suggested Pad Layout



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